EXHIBIT 29

Claim 1	**ACCUSED PRODUCTS**[1]
1.1 An electronic package comprising:	The Accused Products include an electronic package. For example: The Accused Products include an electronic package (e.g., electronic component(s) covered with an electronic shield). As an example, a teardown of Pantech Discover smartphone reveals at least two electronic components covered with an EMI shield. For example only, two of these components are microphones located at the bottom and on the back cover of the phone respectively. The disassembly of Pantech Discover reveals two MEMS microphone packages: Mic-1 "M3K1 4312" (at the bottom of the device) on a flex board and Mic-2 "M3K1 4312" (on the back cover of the device) on the main board.

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[1] The Accused Products include all of the devices listed in the Accused Products Spreadsheet attached to the '551 patent infringement contentions and any other product uncovered during discovery that includes an electronic component surrounded by an EMI shield/Faraday cage.

Claim 1	**ACCUSED PRODUCTS**[1]
	 Front and back View of device [2]

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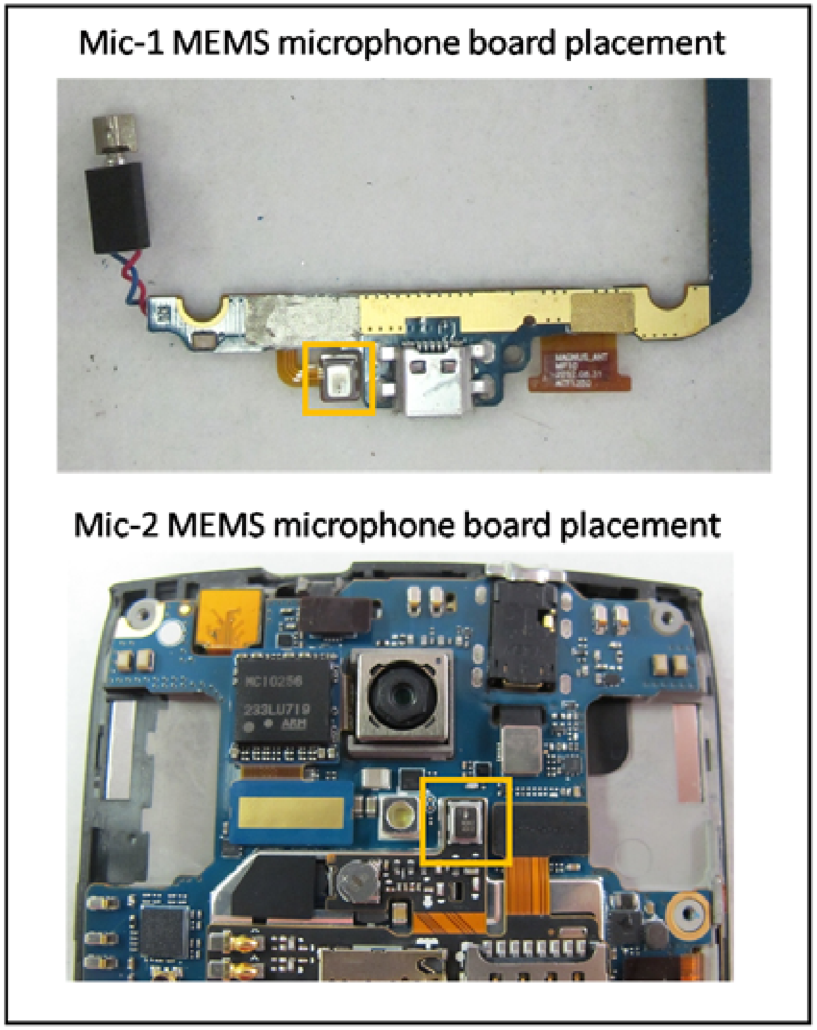
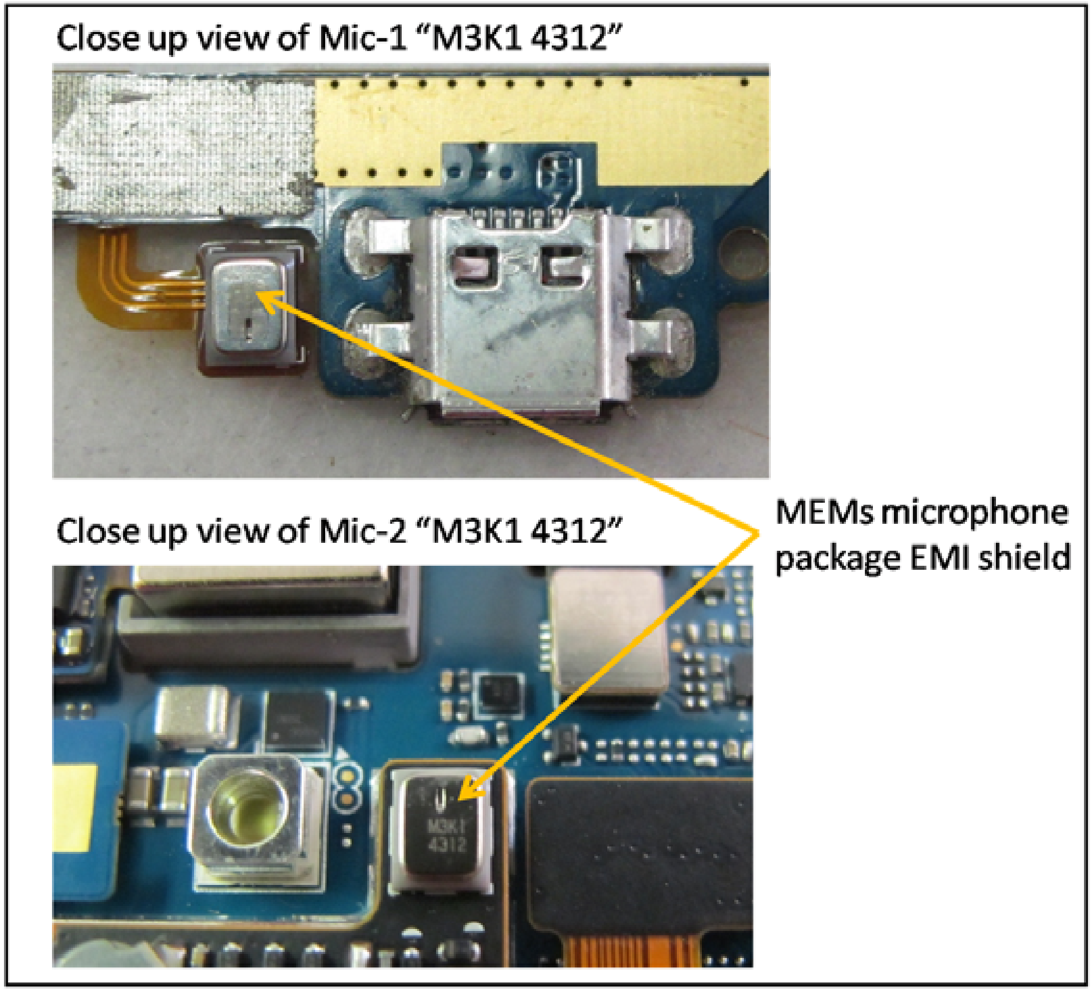
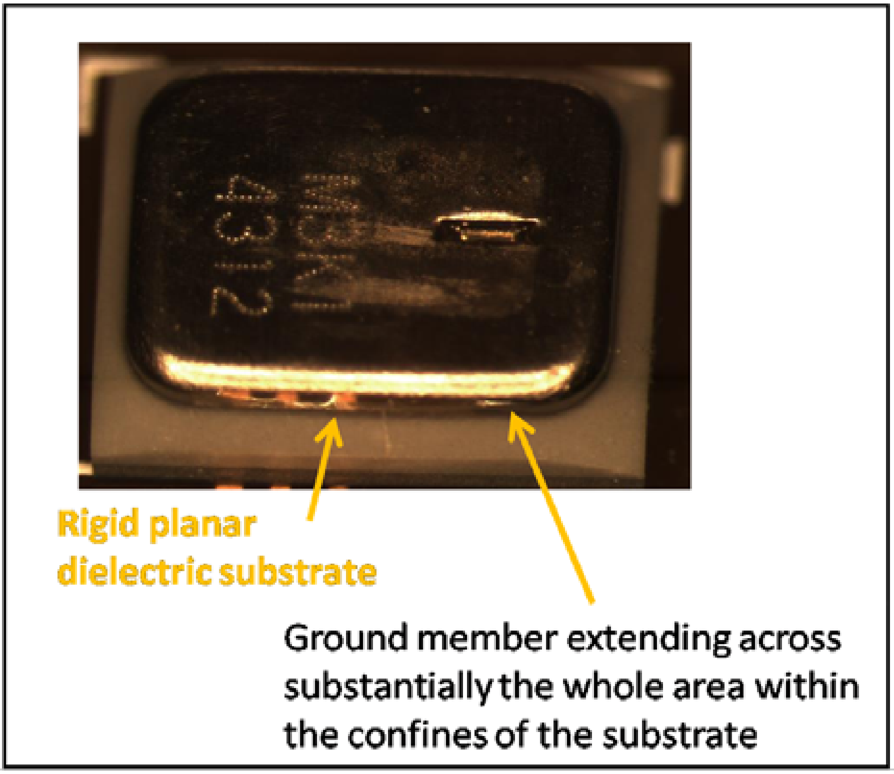
[2] All photographs herein are for the exemplary purpose of showing infringement by the Accused Products.

Claim 1	**ACCUSED PRODUCTS**[1]
	Optical image of the two electronic components covered with an EMI shield   

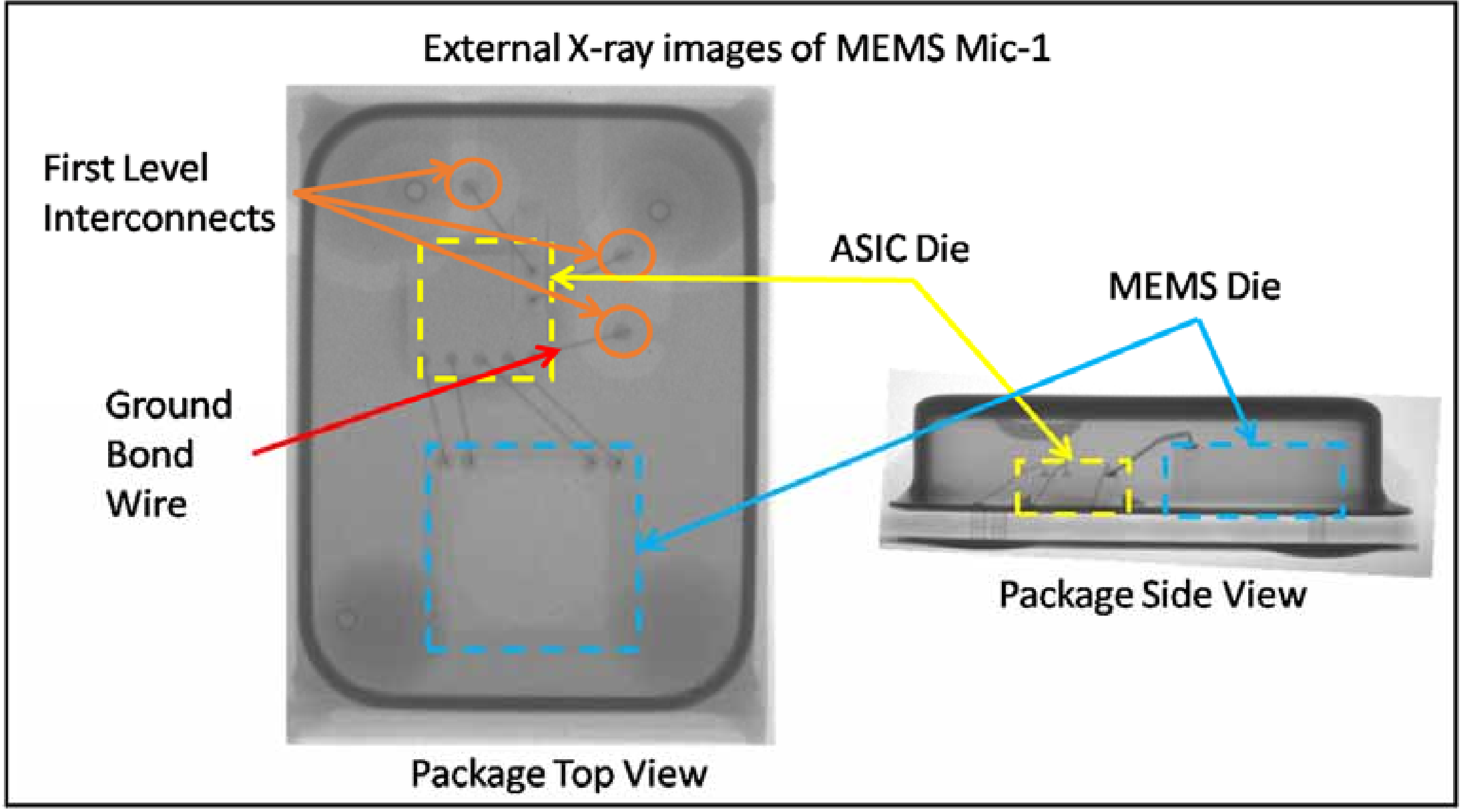
Claim 1	ACCUSED PRODUCTS[1]
	 Front view of device disassembly

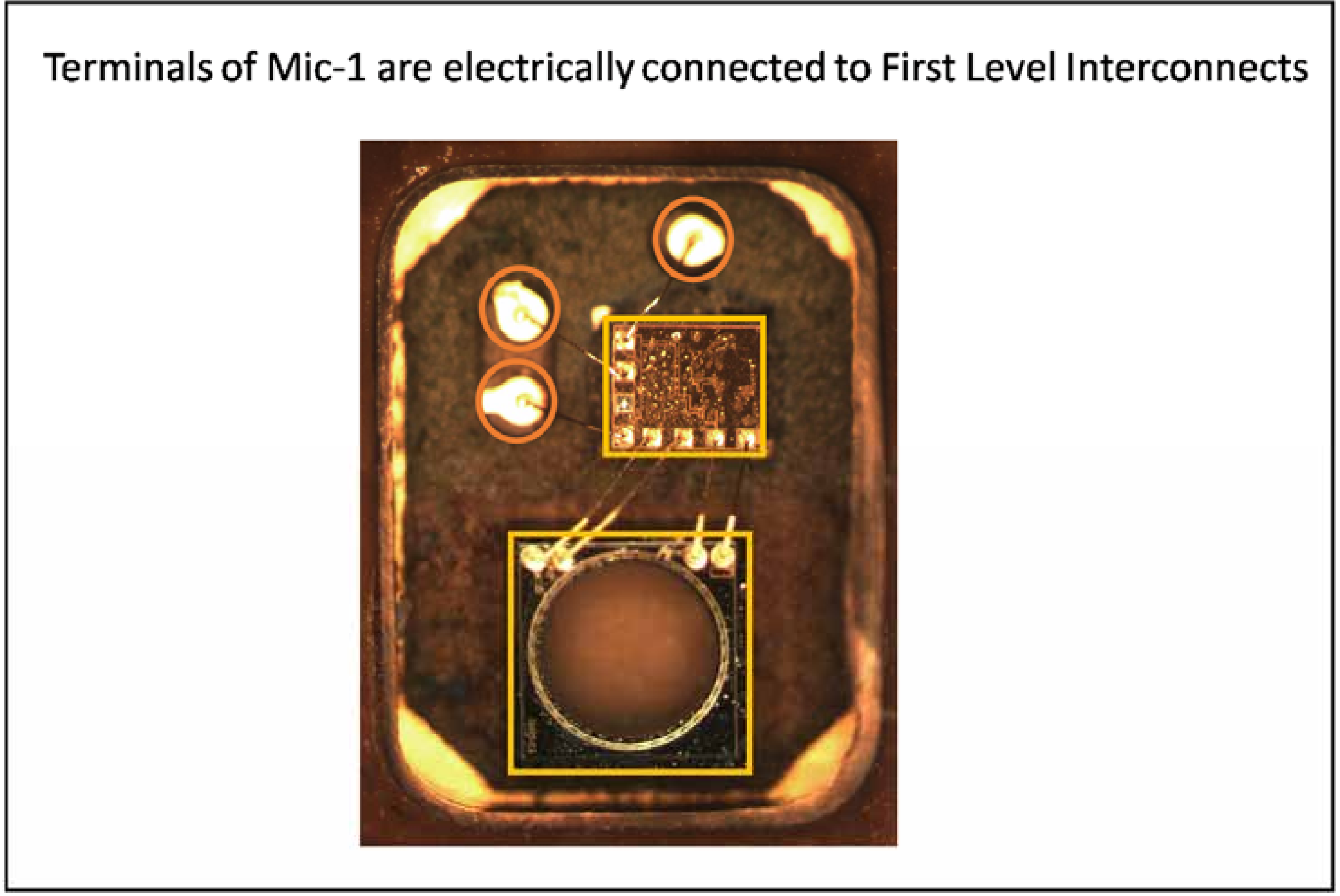
Claim 1	**ACCUSED PRODUCTS[1]**
	 Mic-1 MEMS microphone board placement Mic-2 MEMS microphone board placement

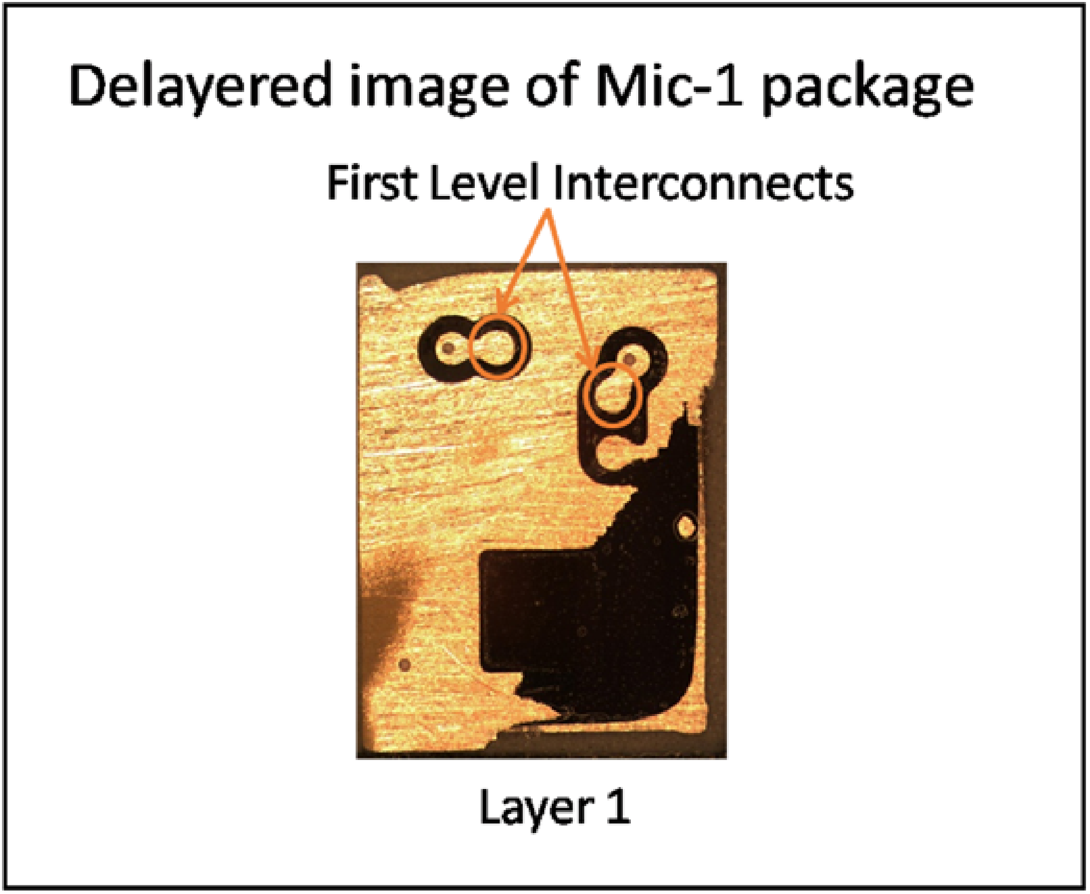
Claim 1	ACCUSED PRODUCTS[1]
	 Rockstar reserves the right to add additional information and infringement theories once discovery begins in this case,

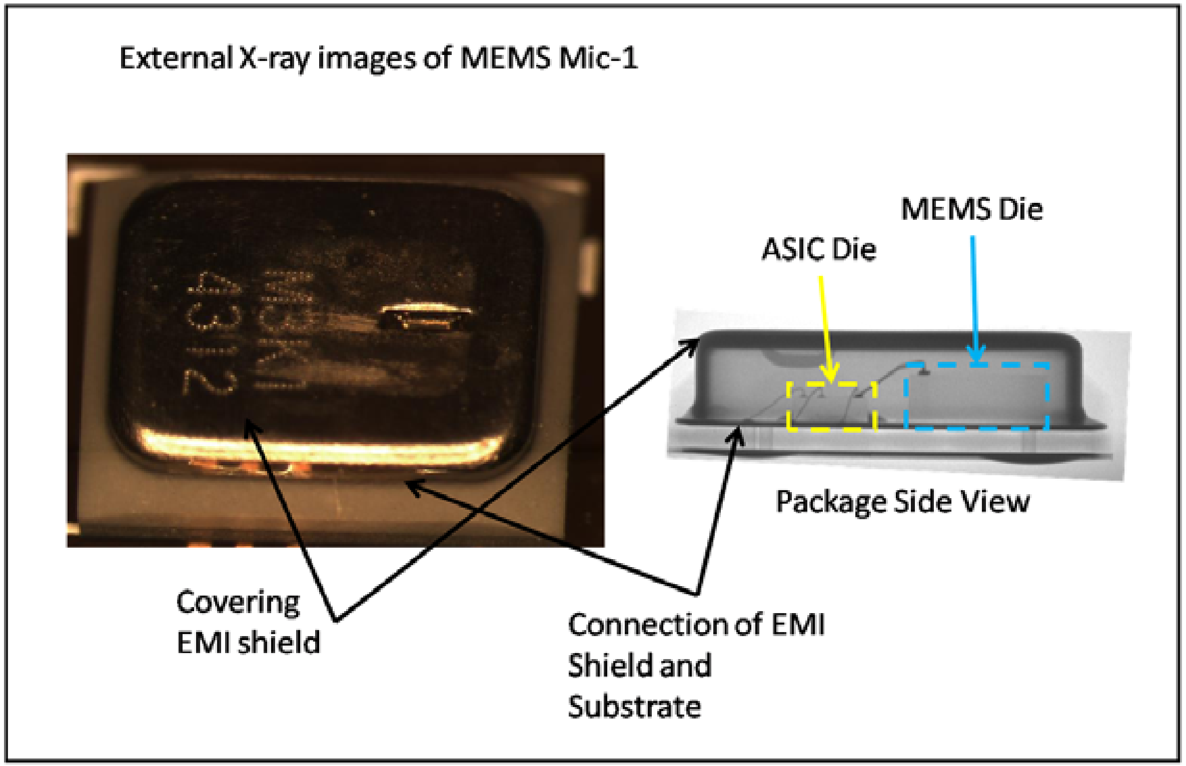
Claim 1	**ACCUSED PRODUCTS**[1]
	particularly once the defendant produces its technical documents and circuit schematics.
1.2 a rigid planar dielectric substrate carrying a ground member extending across substantially the whole area within the confines of the edges of the substrate;	The Accused Products contain a rigid planar dielectric substrate carrying a ground member extending across substantially the whole area within the confines of the edges of the substrate. For example, each of the two electronic components in Pantech Discover comprises a rigid planar dielectric substrate carrying a ground member extending across substantially the whole area of the substrate. The perspective image of the electronic package for Mic-1, for example, shows the rigid planar dielectric substrate and the ground member extending across the area of the substrate. 

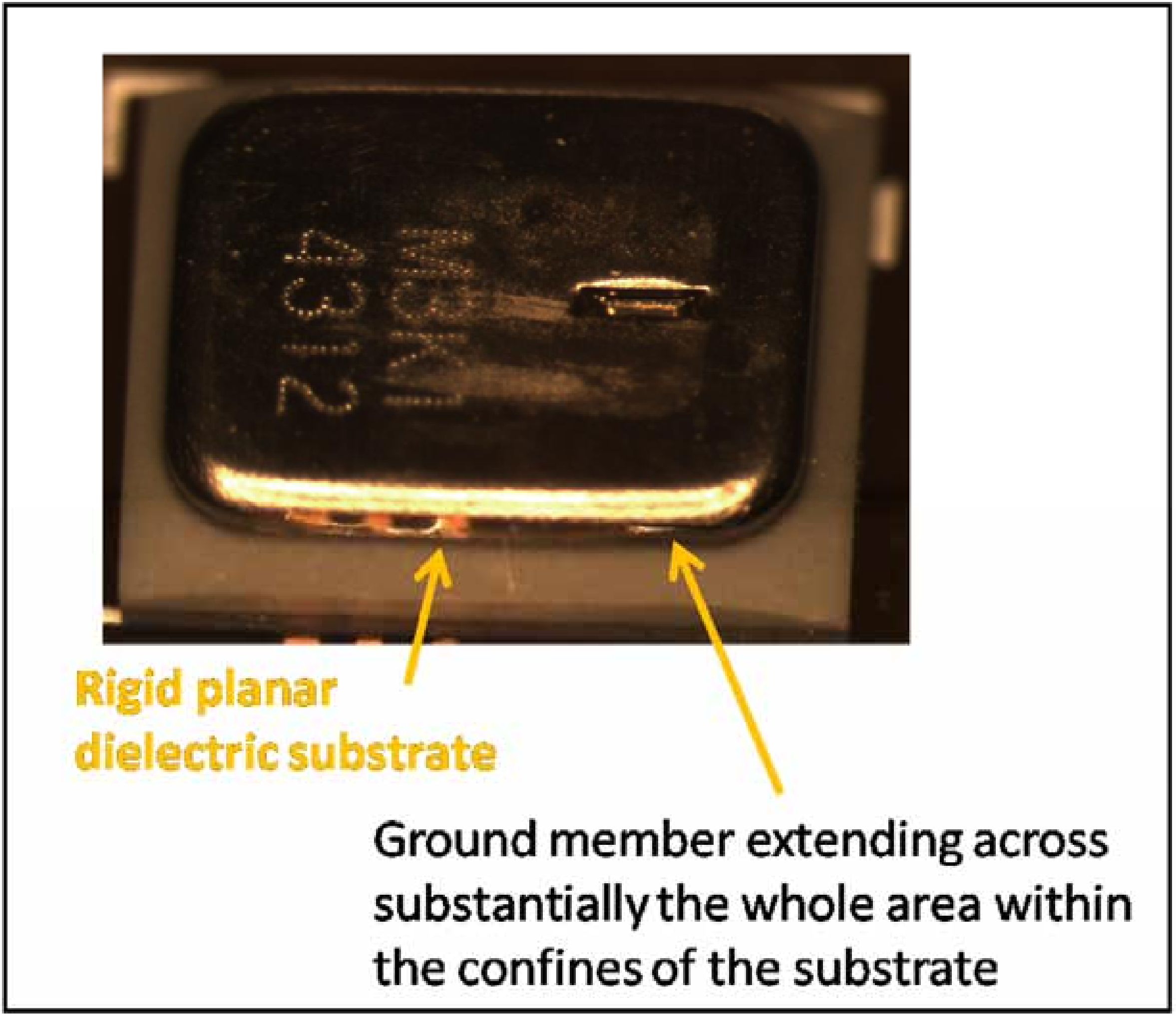
Claim 1	ACCUSED PRODUCTS[1]
	Rockstar reserves the right to add additional information and infringement theories once discovery begins in this case, particularly once the defendant produces its technical documents and circuit schematics.
1.3 an electronic component mounted upon a first side of the substrate and having terminals connected to a plurality of first level terminal interconnects provided upon the first side of the board;	The Accused Products contain an electronic component mounted upon a first side of the substrate and having terminals connected to a plurality of first level terminal interconnects provided upon the first side of the board. For example, each of the two electronic components in Pantech Discover identified is an electronic component mounted upon the top side of the substrate. The external X-ray images for Mic-1, for example, show the ASIC and the MEMS die of Mic-1.

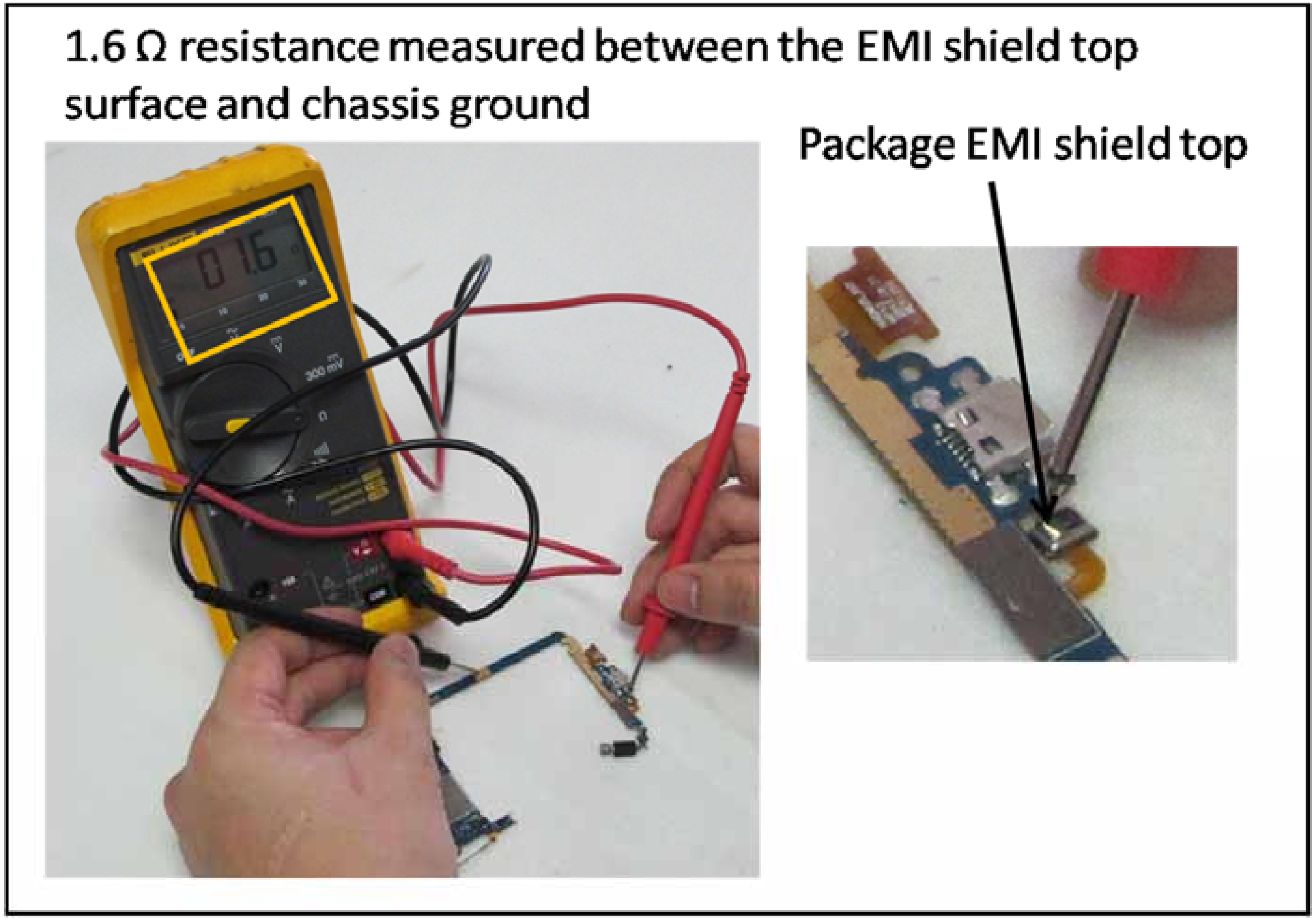
Claim 1	ACCUSED PRODUCTS[1]
	 High resolution images of the decapsulated package also show terminals of Mic-1 that connect to first level interconnects provided on the substrate. Further delayering of the package reveals the first level interconnects on the top layer that are in turn also connected to circuit paths in the substrate.

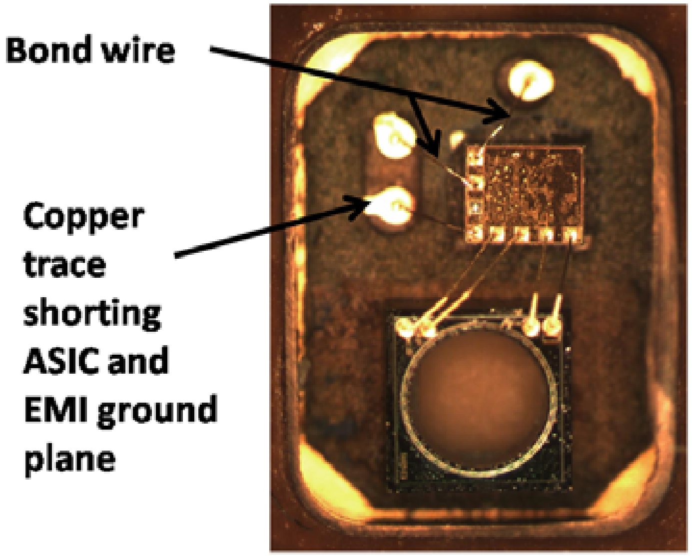
Claim 1	ACCUSED PRODUCTS[1]
	 Terminals of Mic-1 are electrically connected to First Level Interconnects

Claim 1	**ACCUSED PRODUCTS[1]**
	 Delayered image of Mic-1 package First Level Interconnects Layer 1 Rockstar reserves the right to add additional information and infringement theories once discovery begins in this case, particularly once the defendant produces its technical documents and circuit schematics.
1.4 a covering	The Accused Products contain a covering EMI shield extending over the electronic component to locate the electronic

Claim 1	**ACCUSED PRODUCTS[1]**
EMI shield extending over the electronic component to locate the electronic component between the EMI shield and the ground member of the substrate, the EMI shield being electrically interconnected to the ground member of the substrate to form with the ground member, a Faraday cage around the electronic component;	component between the EMI shield and the ground member of the substrate, the EMI shield being electrically interconnected to the ground member of the substrate to form with the ground member, a Faraday cage around the electronic component. For example, each of the two electronic components in Pantech Discover identified above is covered by an EMI shield that locates the electronic component between the EMI shield and the ground member of the substrate. The external X-ray images for Mic-1, for example, shows that the EMI shield extends over the electronic components, the ASIC and the MEMS die of Mic-1. 

Claim 1	ACCUSED PRODUCTS[1]
	 A resistance of 1.6 ohms measured between the top of the EMI shield and the bottom side of the substrate indicates that the

Claim 1	ACCUSED PRODUCTS[1]
	EMI shield is electrically connected to the ground member.  Rockstar reserves the right to add additional information and infringement theories once discovery begins in this case, particularly once the defendant produces its technical documents and circuit schematics.

Claim 1	**ACCUSED PRODUCTS[1]**
1.5 and a plurality of second level interconnects mounted upon a second side of the substrate and electrically interconnected through circuit paths in the substrate to the first level interconnects.	The Accused Products contain a plurality of second level interconnects mounted upon a second side of the substrate and electrically interconnected through circuit paths in the substrate to the first level interconnects. For example, each of the two electronic components in Pantech Discover identified above has a plurality of second level interconnects mounted upon the second side of the substrate and electrically interconnected through circuit paths in the substrate to the first level interconnects. For example, for Mic-1, the bond wires connect to the first level interconnects which in turn are connected to second level interconnect on layer 2 of the package on the second side of the substrate through circuit paths.  Package top internal cavity View (EMI shield removed)

<table>
<tr><th>Claim 1</th><th>ACCUSED PRODUCTS[1]</th></tr>
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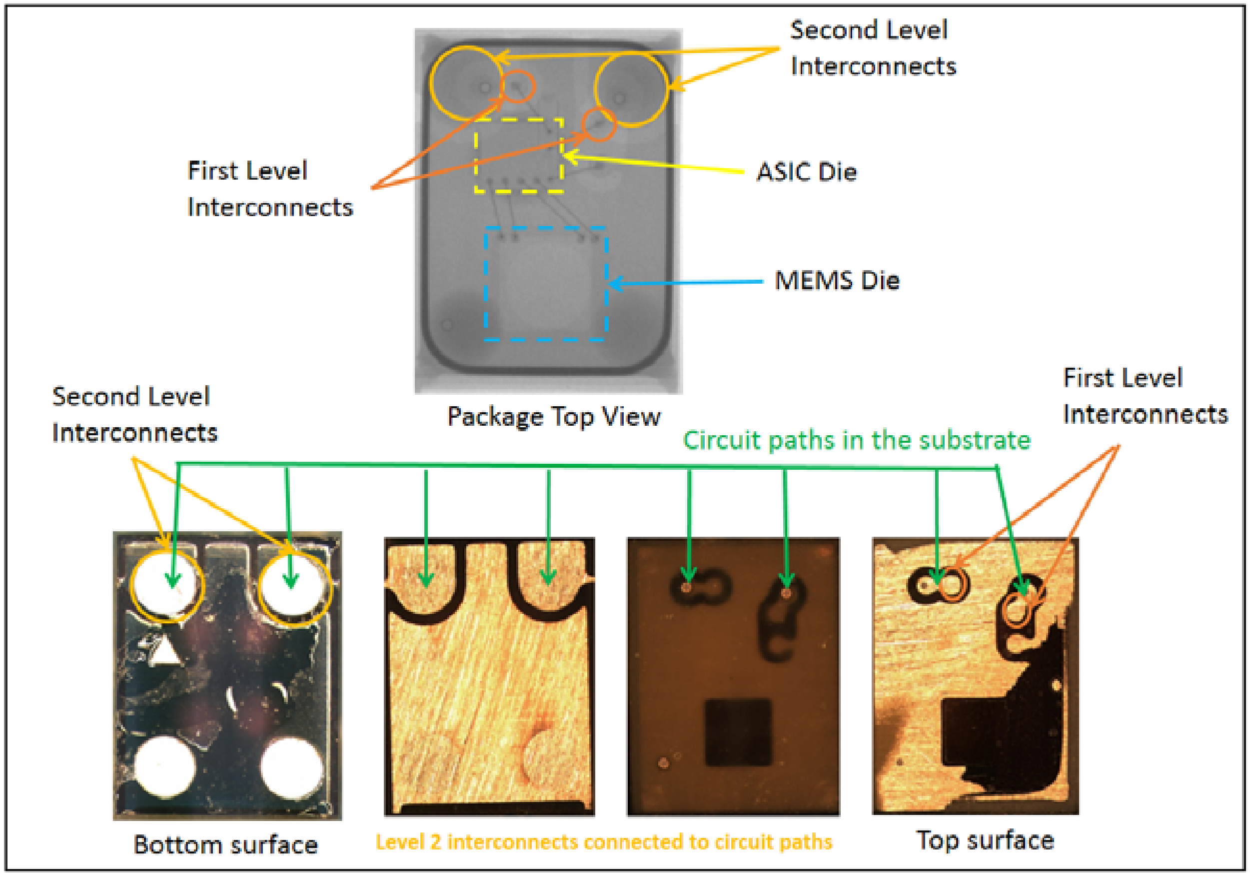
Delayering of Mic-1 package, as an example, shows a plurality of second level interconnects mounted upon the second side of the substrate (Layer 2) and electrically interconnected through circuit paths in the substrate to the first level interconnects. The two layers between Layer 1 on the top side of the substrate and Layer 2 on the bottom side both contain at least two interconnects at the identical locations as Layer 1 and Layer 2 to enable the circuit paths.



Rockstar reserves the right to add additional information and infringement theories once discovery begins in this case,

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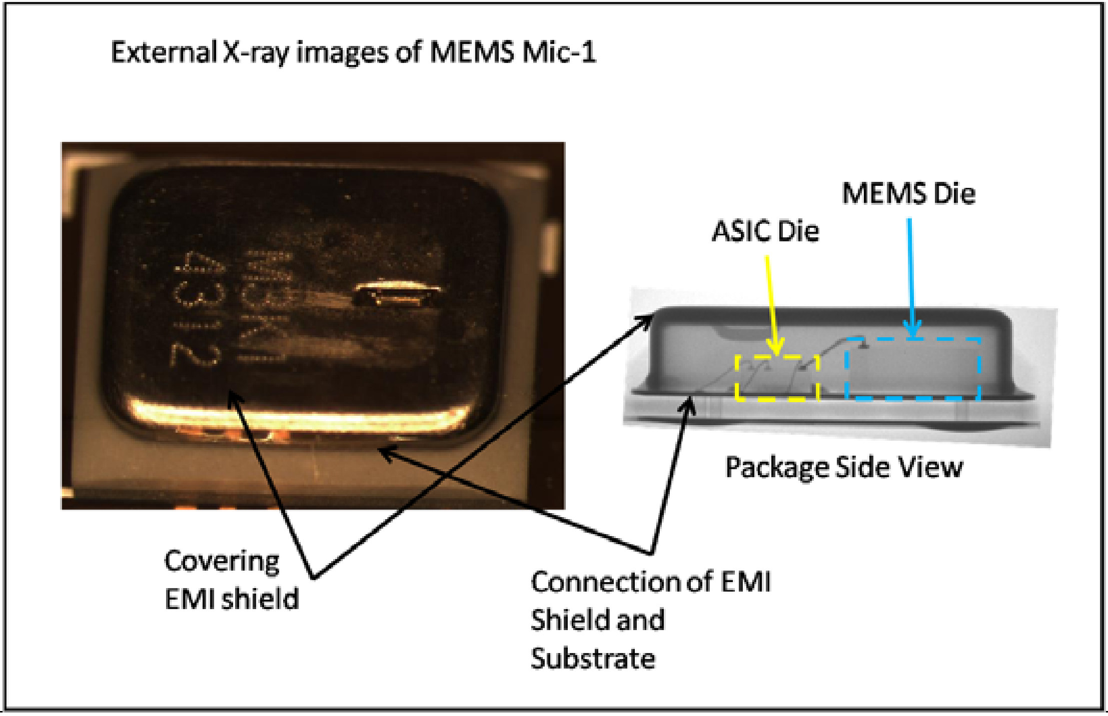
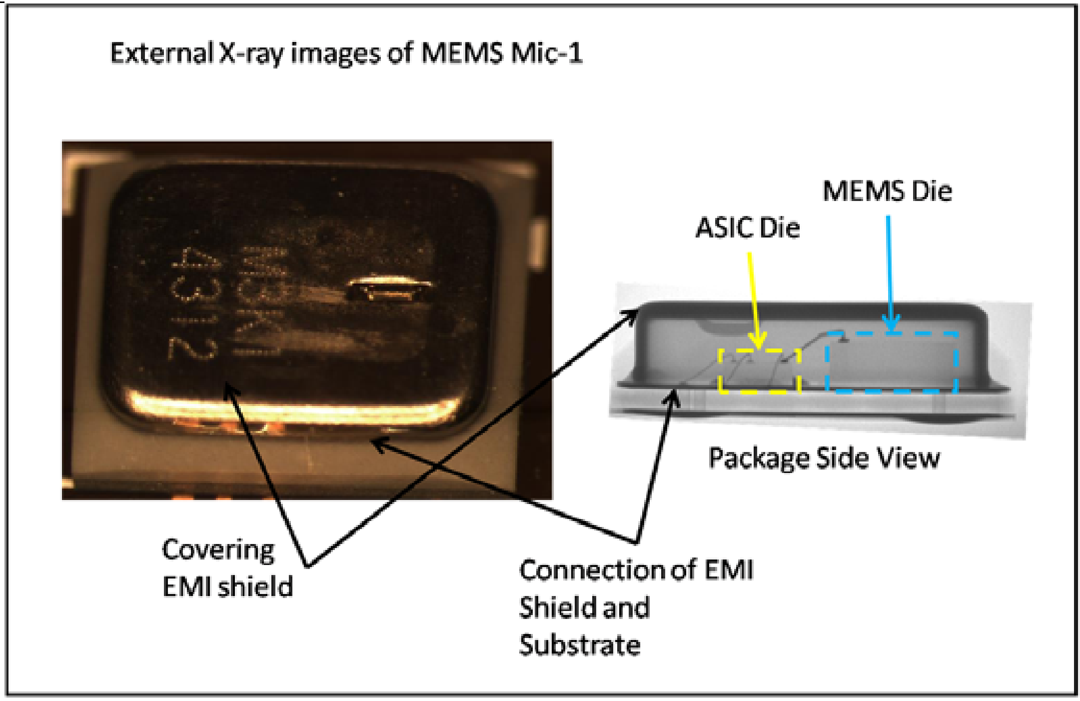
Claim 1	**ACCUSED PRODUCTS[1]**
	particularly once the defendant produces its technical documents and circuit schematics.

Claim 2	**ACCUSED PRODUCTS**
2. A package according to claim 1 wherein the electronic component comprises an integrated circuit component.	The Accused Products comprise a package according to claim 1 wherein the electronic component comprises an integrated circuit component. For example, the Accused Products, including Pantech Discover identified above, contain one or more microphones that comprise an ASIC Die and a MEMS Die covered by an EMI shield. The ASIC Die is an integrated circuit component manufactured specifically for use in the microphone. 

	Rockstar reserves the right to add additional information and infringement theories once discovery begins in this case, particularly once the defendant produces its technical documents and circuit schematics.

Claim 3	**ACCUSED PRODUCTS**
3. A package according to claim 1 comprising two or more electronic components mounted upon the first side of the substrate and at least one of which is an integrated circuit component and all of the components are commonly shielded by the EMI shield.	The Accused Products include a package according to claim 1 comprising two or more electronic components mounted upon the first side of the substrate and at least one of which is an integrated circuit component and all of the components are commonly shielded by the EMI shield. For example, the Accused Products, including Pantech Discover identified above, contain one or more microphones that comprise an ASIC Die and a MEMS Die covered by an EMI shield. The ASIC Die is an integrated circuit component manufactured specifically for use in the microphone.

	 Rockstar reserves the right to add additional information and infringement theories once discovery begins in this case, particularly once the defendant produces its technical documents and circuit schematics.